# -3.3V / -5V Triple ECL Input to PECL Output Translator

#### Description

The MC100EL90 is a triple ECL to PECL translator. The device receives either -3.3 V or -5 V differential ECL signals, determined by the V<sub>EE</sub> supply level, and translates them to standard +5 V differential PECL output signals.

To accomplish the level translation, the EL90 requires three power rails. The V<sub>CC</sub> supply should be connected to the positive supply, and the V<sub>EE</sub> pin should be connected to the negative power supply. The GND pins, as expected, are connected to the system ground plane. Both V<sub>EE</sub> and V<sub>CC</sub> should be bypassed to ground via 0.01  $\mu$ F capacitors.

Under open input conditions, the  $\overline{D}$  input will be biased at  $V_{EE}/2$  and the D input will be pulled to  $V_{EE}$ . This condition will force the Q output to a LOW, ensuring stability.

The V<sub>BB</sub> pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V<sub>BB</sub> as a switching reference voltage. V<sub>BB</sub> may also rebias AC coupled inputs. When used, decouple V<sub>BB</sub> and V<sub>CC</sub> via a 0.01  $\mu$ F capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V<sub>BB</sub> should be left open.

The 100 Series Contains Temperature Compensation

## Features

- 500 ps Propagation Delays
- Operating Range: V<sub>CC</sub>= 4.75 V to 5.25 V; V<sub>EE</sub>= -3.0 V to -5.5 V; GND= 0 V
- Q Output will Default LOW with Inputs Open or at  $V_{\rm EE}$
- Internal Input Pulldown Resistors
- ESD Protection: Human Body Model; > 2 kV, Machine Model; > 200 V
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity Level:

$$Pb = 1$$
  
 $Pb-Free = 3$ 

For Additional Information, see Application Note AND8003/D

- Flammability Rating: UL 94 V-0 @ 1.125 in, Oxygen Index: 28 to 34
- Transistor Count = 261 devices
- Pb-Free Packages are Available\*



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SO-20 WB SUFFIX CASE 751D

## MARKING DIAGRAM\*



\*For additional marking information, refer to Application Note AND8002/D.

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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\* All  $V_{CC}$  pins are tied together on the die. Warning: All  $V_{CC}$ ,  $V_{EE}$ , and GND pins must be externally connected to Power Supply to guarantee proper operation.



#### **Table 2. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	PECL Mode Power Supply	V <sub>EE</sub> = 0 V		8 to 0	V
$V_{EE}$	NECL Mode Power Supply	$V_{CC} = 0 V$		-8 to 0	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V <sub>EE</sub> = 0 V V <sub>CC</sub> = 0 V	$\begin{array}{c} V_{I} \leq V_{CC} \\ V_{I} \geq V_{EE} \end{array}$	6 to 0 –6 to 0	V V
l <sub>out</sub>	Output Current	Continuous Surge		50 100	mA mA
I <sub>BB</sub>	V <sub>BB</sub> Sink/Source			± 0.5	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-20 SOIC-20	90 60	°C/W °C/W
$\theta_{\text{JC}}$	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-20	30 to 35	°C/W
T <sub>sol</sub>	Wave Solder Pb Pb-Free			265 265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

		–40°C			25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>CC</sub>	V <sub>CC</sub> Power Supply Current			24		20	24			26	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 2)	3915	3995	4120	3975	4045	4120	3975	4050	4120	mV
V <sub>OL</sub>	Output LOW Voltage (Note 2)	3170	3305	3445	3190	3295	3380	3190	3295	3380	mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Output parameters vary 1:1 with V<sub>CC</sub>. V<sub>CC</sub> can vary  $\pm$  0.5 V.

2. Outputs are terminated through a 50  $\Omega$  resistor to V\_{CC} – 2.0V.

PIN	FUNCTION				
Dn, Dn	ECL Inputs				
Qn, <u>Qn</u>	PECL Outputs				
ECL V <sub>BB</sub>	ECL Reference Voltage Output				
V <sub>CC</sub>	Positive Supply				
V <sub>EE</sub>	Negative Supply				
GND	Ground				

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		<b>−40°C</b>			2	25°C		٤			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>EE</sub>	V <sub>EE</sub> Power Supply Current			8.0		6.0	8.0			8.0	mA
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	-1810		-1475	-1810		-1475	-1810		-1475	mV
ECL V <sub>BB</sub>	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 4)										
	Vpp < 500 mV	V <sub>EE</sub> + 1.3		-0.4	V <sub>EE</sub> + 1.2		-0.4	V <sub>EE</sub> + 1.2		-0.4	V
	$Vpp \ge 500 \text{ mV}$	V <sub>EE</sub> + 1.5		-0.4	V <sub>EE</sub> + 1.4		-0.4	V <sub>EE</sub> + 1.4		-0.4	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current	0.5			0.5			0.5			μA

## Table 4. NECL DC CHARACTERISTICS V<sub>CC</sub> = 5.0 V; V<sub>EE</sub> = -5 V; GND = 0 V (Note 3)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Input parameters vary 1:1 with GND. V<sub>EE</sub> can vary -3.0 V / -5.5 V. 4. V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>. V<sub>IHCMR</sub> max varies 1:1 with GND.

## Table 5. AC CHARACTERISTICS V<sub>CC</sub> = 4.5 to 5.5 V; V<sub>EE</sub> = -3.0 to -5.5 V; GND = 0 V

			-40°C		25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>max</sub>	Maximum Toggle Frequency		560			650			700		MHz
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation Delay Differential D to Q S.E.	390 340		590 640	420 370		620 670	460 410		660 710	ps
tskew	Skew Output-to-Output (Note 5) Part-to-Part (Differential Configuration) (Note 5) Duty Cycle (Differential Configuration) (Note 6)		20 25	100 200		20 25	100 200		20 25	100 200	ps
t <sub>JITTER</sub>	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
V <sub>PP</sub>	Input Swing (Note 7)	150		1000	150		1000	150		1000	mV
t <sub>r</sub> t <sub>f</sub>	Output Rise/Fall Times Q (20% – 80%)	230		500	230		500	230		500	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Skews are valid across specified voltage range, part-to-part skew is for a given temperature.

6. Duty cycle skew is the difference between a TPLH and TPHL propagation delay through a device.

7. V<sub>PP</sub>(min) is the minimum input swing for which AC parameters are guaranteed. The device has a DC gain of ≈40.

## MC100EL90



Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D - Termination of ECL Logic Devices.)

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC100EL90DW	SOIC-20	38 Units / Rail
MC100EL90DWG	SOIC-20 (Pb-Free)	38 Units / Rail
MC100EL90DWR2	SOIC-20	1000 / Tape & Reel
MC100EL90DWR2G	SOIC-20 (Pb-Free)	1000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **Resource Reference of Application Notes**

AN1405/D	-	ECL Clock Distribution Techniques
AN1406/D	-	Designing with PECL (ECL at +5.0 V)
AN1503/D	-	ECLinPS <sup>™</sup> I/O SPiCE Modeling Kit
AN1504/D	-	Metastability and the ECLinPS Family
AN1568/D	-	Interfacing Between LVDS and ECL
AN1672/D	-	The ECL Translator Guide
AND8001/D	-	Odd Number Counters Design
AND8002/D	-	Marking and Date Codes
AND8020/D	-	Termination of ECL Logic Devices
AND8066/D	-	Interfacing with ECLinPS
AND8090/D	-	AC Characteristics of ECL Devices

#### PACKAGE DIMENSIONS

SO-20 WB CASE 751D-05



- NOTES: 1. DIMENSIONS ARE IN MILLIMETERS. 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION. 3
- MAXIMUM MOLD PROTRUSION 0.15 PER SIDE. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDRIGN AT MAXIMUM MATERIAL 5 CONDITION.

	MILLIMETERS							
DIM	MIN	MAX						
Α	2.35	2.65						
A1	0.10	0.25						
В	0.35	0.49						
C	0.23	0.32						
D	12.65	12.95						
Ε	7.40	7.60						
е	1.27	BSC						
Н	10.05	10.55						
h	0.25	0.75						
L	0.50	0.90						
θ	0 °	7 °						

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